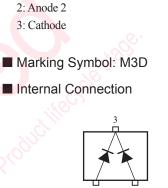
MA3S795E (MA795WK)

Silicon epitaxial planar type

For switching

Features

- High-density mounting is possible
- \bullet Forward voltage V_F , optimum for low voltage rectification: $V_F < 0.3 \ V$
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}
- Absolute Maximum Ratings $T_a = 25^{\circ}C$ Unit Parameter Symbol Rating V Reverse voltage V_R 30 30 V Maximum peak reverse voltage V_{RM} Single 30 Forward current I_{F} mA 20 Double Single 150 Peak forward current I_{FM} mA Double 110 125 °C Junction temperature Ti Storage time T_{stg} -55 to +125 °C



Package

Pin Name

1: Anode 1

SSMini3-F2

Code

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

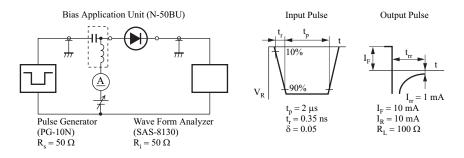
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _{F1}	I _F = 1 mA	N. K.		0.3	V
	V _{F2}	$I_F = 30 \text{ mA}$	50, 51	27	1.0	
Reverse current	IR	$V_R = 30 V$	Rice		30	μΑ
Terminal capacitance	Ct	$V_R = 1 V, f = 1 MHz$,2	1.5		pF
Reverse recovery time *	t _{rr}	$I_{F} = I_{R} = 10 \text{ mA}, I_{rr} = 1 \text{ mA},$ $R_{L} = 100 \Omega$		1.0		ns
Detection efficiency	η	$V_{IN} = 3 V_{(peak)}$, f = 30 MHz R _L = 3.9 kΩ, C _L = 10 pF		65		%

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 2 GHz

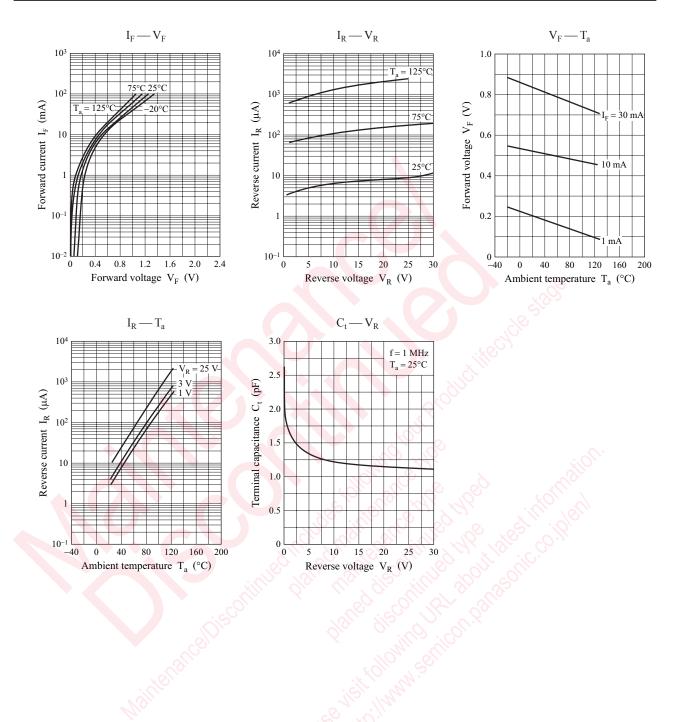
4. *: t_{rr} measurement circuit



Note) The part number in the parenthesis shows conventional part number.

MA3S795E

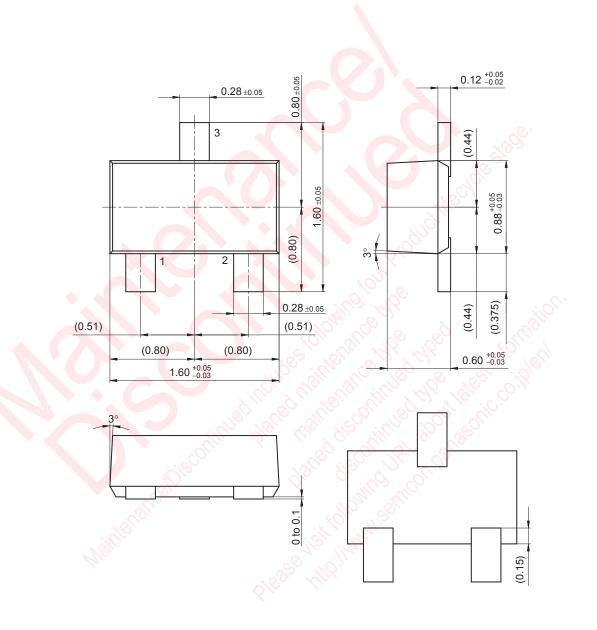
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SSMini3-F2

Unit: mm



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